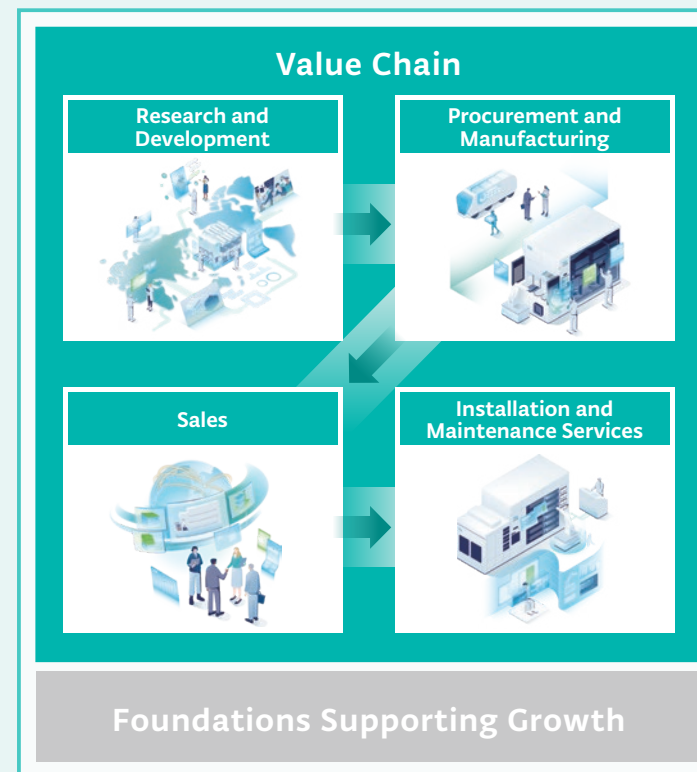


Chapter 3

Initiatives in the Value Chain

- 29 Research and Development
- 33 Procurement and Manufacturing
- 37 Sales
- 41 Installation and Maintenance Services



Corporate Value Enhancement

Tokyo Electron leverages its unique strengths to build a superior business model and develops a value chain spanning research and development, procurement and manufacturing, sales, and installation and maintenance services, each under the leadership of responsible officers. We advance initiatives on key themes for medium- to long-term value creation throughout the entire Group and strive to continuously enhance corporate value.

Research and Development

Message

In the semiconductor industry, where technological innovation advances rapidly, companies are expected to proactively develop and commercialize high-value-added technologies and products. We backcast from our vision of the future world and technologies 10 or 20 years ahead, and conduct high-value-added research and development (R&D) aimed at technological inflection points. Based on a medium- to long-term development roadmap, we invest our resources to create even more competitive technologies and services. In addition, by actively leveraging AI-driven advances to further enhance sophistication and efficiency, we will further accelerate our development.

Based on the value of "Digital & Green," balancing environmental considerations with the advancement of manufacturing technology is essential for the future development of the semiconductor industry and for our own growth as well. Recruiting and developing outstanding talent is important for realizing this future. Going forward, we aim to blend the experienced talent that has supported the industry to date with talent across a wide range of specialties, to further strengthen our R&D and enhance our corporate value.



Sumie Segawa

Vice President & General Manager
Division Officer, Corporate Innovation Division



Research and Development

Key Themes for
Medium- to Long-
term Value
Creation

Timely development of
high-value-added
technologies and products
through promotion of
Shift Left

Further pursuing
development efficiency and
strengthening human
resource development

Management Resources to Be Invested

Intellectual capital

R&D investment
Over five years, beginning in fiscal 2025

more than
1.5 trillion yen



Intellectual capital

R&D sites

19
(8 in Japan and 11 overseas)



Human capital

**Human resources possessing
knowledge in a variety of
specialized fields**

related to semiconductor
production equipment



Differentiation Points

**Strategic Research and
Development**

Development Efficiency

Collaboration System

Intellectual Property

Intellectual Property and Other
Intangible Assets **P. 47**

Value Created

Innovative, high-value-added
unique technologies
that contribute to leading-edge
semiconductor production

Equipment highly advantageous
such as in higher throughput, a higher
utilization rate and smaller space
requirements

Environmental performance
contributing to the achievement
of net zero

Related Main Risks

Risk Management **P. 65-66**

Risk **2**

**Research and
Development**

Risk **9**

**Intellectual
Property Rights**

Risk **11**

**Human
Resources**

Risk **14**

M&A

Research and Development

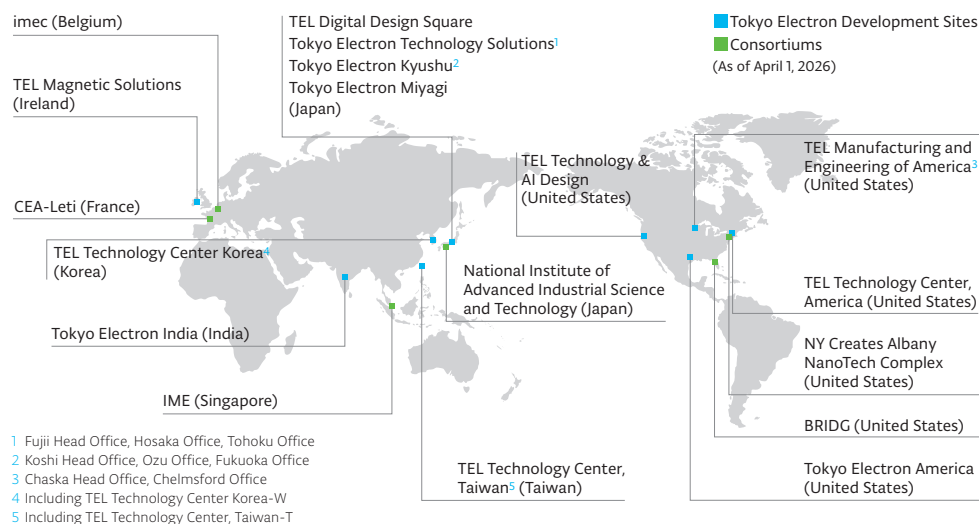
Key
Theme

Timely development of high-value-added technologies and products through promotion of Shift Left / Further pursuing development efficiency and strengthening human resource development

Strategic R&D Initiatives

To launch next-generation products with high added value onto the market in a timely manner, our Corporate Innovation Division leads strategic R&D in collaboration with our development sites and consortiums in Japan and overseas.

R&D Sites



R&D for High NA EUV Technology Toward Practical Application

To support implementation of leading-edge processes using extreme ultraviolet (EUV) technology, we are not only contributing to performance improvements of individual exposure systems, but also positioning integrated process design that includes auxiliary processes such as coating and developing, masking, and measurement and correction, at the core of our R&D. Specifically, we are working to evaluate the performance of photoresists (light-sensitive materials), optimize coating/development and process conditions, and improve measurement accuracy of fine patterns after exposure. In the coating process, we aim to achieve uniform film

thickness through coater/developer control and process parameter optimization. In terms of materials, we are evaluating combinations of high-sensitivity, stable photoresists. To reduce the number of trial runs and improve efficiency of these validations, we are implementing planned experimental design and utilizing digital twin technology and analysis tools.

To support high numerical aperture (High NA) EUV technology, we are evaluating the interactions among reticles, photoresists, and exposure conditions to achieve higher resolution. Specifically, we analyze the effects of wafer patterns on fine patterning, based on data from production equipment and empirical results, and build knowledge for improving mask inspection methods*. By evaluating combinations of optical properties and process responses, we are also working to verify process conditions and equipment control methods that enhance resolution while maintaining throughput.

Over recent years, the major research facilities and leading semiconductor manufacturers around the world have been accelerating adoption of High NA EUV technology as they intensify efforts toward further scaling. In this context, we are focusing on optimization of coating and development, as well as process steps and metrology, in the High NA area. Utilizing data from production equipment and pilot lines, we are validating evaluation methods and equipment control strategies to improve process stability and throughput, while also strengthening our framework to resolve implementation challenges at an early stage through joint research.

In this way, we are enhancing comprehensive support capabilities across materials, equipment, and processes for leading-edge logic and high-density memory beyond the 2 nm nodes, while also enabling further performance improvements through continued scaling.

We are also optimizing the frontend and backend processes of EUV lithography. By taking account of how processes such as film deposition, etching, and cleaning affect the final outcome after exposure, we offer approaches to improve yield. We validate these approaches through joint experiments with semiconductor manufacturers, material suppliers, and research institutions, and we proactively work to address potential challenges during mass production.

* Mask inspection methods: Technologies for inspecting defects, dimensional accuracy, and misalignment of photomasks used to pattern semiconductor circuit features

Research and Development

Key Theme

Timely development of high-value-added technologies and products through promotion of Shift Left / Further pursuing development efficiency and strengthening human resource development

Equipment and Process Technologies for Advanced Packaging and Panel-level Packaging

In semiconductor manufacturing, the importance is increasing of not only feature scaling but also advanced packaging that expands functionality through combinations of multiple chips. We are incorporating advanced technologies developed in deposition, coating/development, etching, cleaning and other frontend processes, as well as alignment technologies, into our backend equipment. We are also focusing on R&D to enhance reliability of bonding quality, alignment accuracy, and wafer thinning processes. In the area of bonding, we are developing technologies that pre-treat the bonding surfaces to improve bonding strength and electrical connectivity, while also working on process condition optimization to reduce distortion after bonding and equipment design to ensure stable bonding quality. To improve positioning accuracy, in addition to utilizing measurement and analysis technologies such as infrared cameras, high-precision sensors, and image-processing algorithms, we are conducting R&D toward stable high-precision packaging. In the wafer thinning process, we are working to optimize conditions in each process, from back grinding to chemical mechanical polishing (CMP) and edge trimming, to improve yields.

Panel-level packaging has been attracting attention over recent years. While batch production of a large number of packages on large panels is expected to improve productivity, the method also comes with a range of challenges, including panel warping, chip misalignment, and film thickness and wiring uniformity. We are therefore applying panel transfer and warpage correction technologies to achieve uniform coating, and working with material manufacturers and consortiums to confirm suitability for mass production. To improve yields as well, we are working to enhance production efficiency and product reliability by improving screening of good units and thermal management and improving testing accuracy.

Improving Productivity through Panel-level Packaging

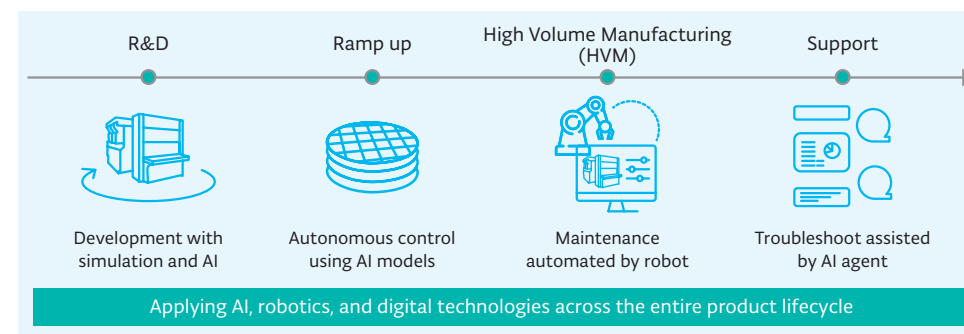


Epsira™-centered Acceleration of DX and Innovation

To meet the increased demand driven by the growth of semiconductor fabs, we are developing our Epsira™ DX solutions in a wide range of areas, from R&D to start-up and mass production after installing the equipment at our customers' sites.

In R&D, we are actively utilizing simulation and AI to improve development efficiency. We are also using digital simulations to identify the optimal dimensions and shapes for process stability in the virtual space, prior to prototyping, when designing the chambers of semiconductor production equipment. In this way, we are using simulation and AI to optimize design as we work to minimize prototyping and reduce development lead time. During process development, the increasing complexity and scaling of device structures is dramatically increasing the number of evaluation man-hours and development lead time required for achieving the desired results. In contrast, we are also adopting process informatics in an effort to minimize experimentation and efficiently achieve our objectives. We are also using materials informatics to search for new materials from among a vast range of candidate materials. We believe that these initiatives will help us achieve a high success rate in development, and reduce environmental impact by reducing the number of prototypes and experiments needed. In addition to developing our own Group DX platform to shorten research and development cycle times, we are also promoting its use and adoption across the entire company.

Epsira™ Deployment



Procurement and Manufacturing

Message

Tokyo Electron focuses on achieving sustainable and resilient manufacturing. The Corporate Production Division promotes supply chain visualization and optimization through joint operational systems with manufacturing companies, working to strengthen stable procurement, regulatory compliance, and risk parts management. By sharing order forecast information between sales and manufacturing divisions, we seek to reduce parts shortages and leveling production, and we work with suppliers on technological innovation and environmental impact reduction to achieve net zero emissions. In addition, we are conducting initiatives such as Smart Production and One-touch Start-up as well as technology standardization and the introduction of generative AI to dramatically increase production quality and productivity and achieve world-class manufacturing operations.



Shinichi Hayashi

Corporate Director
Corporate Officer, Development & Production
Executive Vice President & General Manager
Division Officer, Development & Production 3rd Division
Division Officer, Corporate Production Division



Procurement and Manufacturing

Key Themes for
Medium- to Long-
term Value
Creation

Co-creation of value through
solid relationships of mutual
trust with suppliers

World-class manufacturing
operations through the
realization of Smart
Production concepts

Management Resources to Be Invested

Manufactured capital/Human capital

**Many years of know-how
(people and products)**
in semiconductor production
equipment business



Manufactured capital

Manufacturing core systems
that make full use of the latest
digital technologies



Social and relationship capital

**Solid cooperative
working relationships**
with suppliers



Differentiation Points

Quality and Reliability

**Sustainable Procurement
Activities**

**Pursuit of Efficient
Productivity**

**Initiatives to Achieve
Net Zero**

Value Created

**High-quality and superior-
reliability products**
incorporating leading-edge technologies

**Shortening of production
lead times**
through stable and efficient
manufacturing operations

**Contributions to the preservation
of the global environment**

Related Main Risks

Risk Management P. 65-66

Risk **4**
**Procurement,
Production, and Supply**

Risk **5**
Safety

Risk **6**
Quality

Risk **7**
**Environmental
Issues**

Procurement and Manufacturing

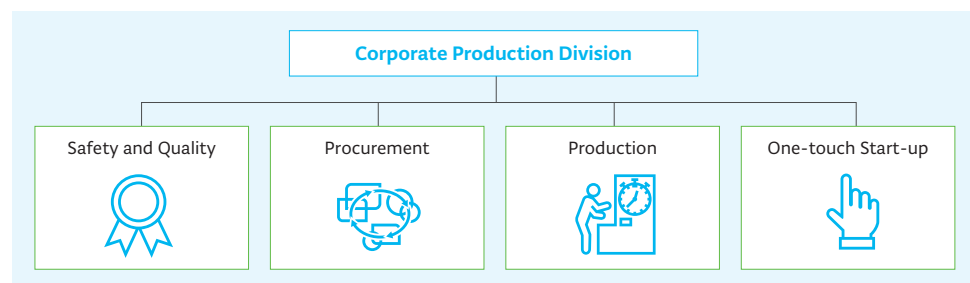
Key
Theme

Co-creation of value through solid relationships of mutual trust with suppliers

Sustainable Manufacturing Strategies

In order to conduct even more efficient manufacturing of high-quality products, the Corporate Production Division is building joint operational systems with four leading manufacturing companies in Japan and overseas, achieving rapid coordination and sustainable manufacturing across four themes: Safety and Quality, Procurement, Production, and One-touch Start-up.

We are also forming supply chain clusters near each manufacturing company. We are decreasing environmental impacts through reduced shipping distances and other effects of shared deliveries in production, procurement, and delivery while promoting high-added-value manufacturing that is consistent throughout, including design and development, in partnership with suppliers.



Communication with Our Suppliers

Believing that strong partnerships with our suppliers are vital for building sustainable supply chains, we create various opportunities for communication.

Name	Frequency	Organizer	Target Companies	Main Contents
TEL Partners' Day	Annually	Corporate Production Division	Partner companies	Management policy, technological trends, procurement policies etc.
Production update briefing	Twice annually	Each manufacturing site	Main suppliers	Production plans, sustainability initiatives
TEL Supplier Summit	Irregular	Corporate Production Division	Important suppliers concerned with core technologies	Discussions on technological situations, environmental initiatives

We support the intent of the Council on Promoting Partnership Building for Cultivating the Future promoted by the Cabinet Office, the Ministry of Economy, Trade and Industry, and the Small and Medium Enterprise Agency and announced our Declaration of Partnership Building. In conjunction with the revision of the Basic Policy based on the Small and Medium-sized Enterprises Business Enhancement Act, we revised our declaration on April 10, 2026. We will continue striving to improve added value in the supply chain and build sustainable supply chains through cooperation and mutual prosperity with our suppliers.

On TEL Partners' Day held in fiscal 2026, we recognized six suppliers that made outstanding contributions to production activities as Excellent Partners and two suppliers that cooperated with our environmental and E-COMPASS activities as Environmental Partners.



A scene from TEL Partners' Day



The Excellent Partner award plaque



The Environmental Partner award plaque

Procurement and Manufacturing

Key
Theme

World-class manufacturing operations through the realization of Smart Production concepts

World-class Manufacturing Operations

In order to respond flexibly to changes in internal and external environments and to meet customer expectations, Tokyo Electron is advancing initiatives under the following themes with the objective of achieving world-class manufacturing operations, primarily through the Corporate Production Division.



Safety and Quality

By promoting Shift Left (front-loading), Tokyo Electron is working to prevent risk identification gaps by transitioning from a project-specific risk identification to a company-wide design process that centralizes and shares information on risks throughout the organization. We also established new KPIs relating to equipment defects and field defects and are rolling these out horizontally at sites while performing KPI trend analysis throughout the Group to achieve improvements and enhance quality even more.



Procurement

Supply chain management is becoming even more important in the semiconductor production equipment industry. We are working to visualize our supply chain so that we can achieve stable procurement, comply with laws and regulations, and identify risk components, as well as optimize procurement processes, parts costs, and parts inventories through coordination among manufacturing companies. In addition, we are implementing sustainable procurement activities throughout the supply chain while fulfilling our social responsibility and giving due consideration to the environment.



One-touch Start-up

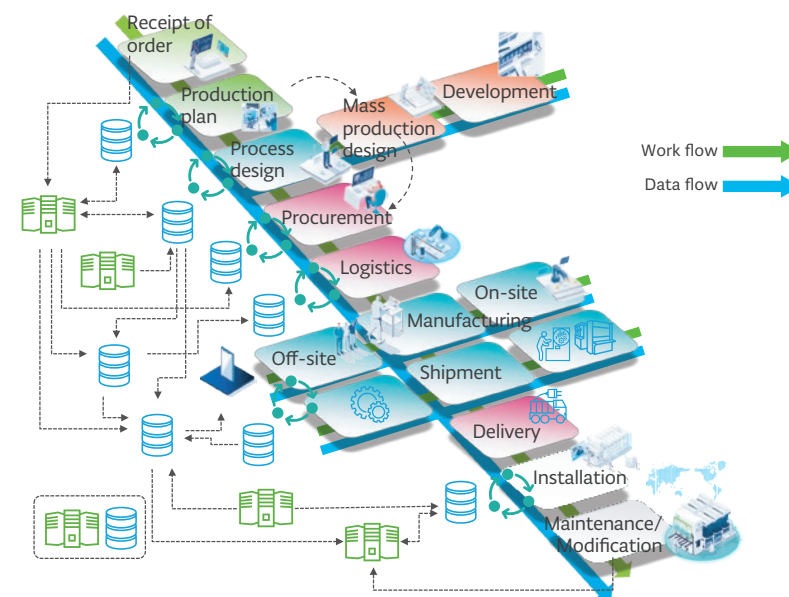
To achieve One-touch Start-up, we are simplifying installation and connection work, and developing measurement and control technologies to shorten startup times, enhance work quality, and reduce the risks of human error and operational mistakes. By automating and autonomously controlling process tuning after equipment startup, we deliver high-quality equipment with shorter lead times and contribute to even higher productivity on the part of customers by increasing equipment utilization rates through reduced maintenance time.



Production

To achieve the Smart Production concept, we are implementing production innovation that covers the entire value chain from order receipt and manufacturing to equipment installation and maintenance at customers' sites. Through the linking and utilization of production data and the visualization of information, we are improving product and operational quality while pursuing substantial increases in productivity by promoting automation and standardization.

Smart Production Vision



Sales

Message



Makoto Oba

Vice President & General Manager
Division Officer,
Account Sales Division

With the advent of AI, we aim to leverage our cutting-edge product portfolio to address the challenges of enhancing semiconductor performance by providing the Best Products and Best Technical Service not only for a single process, but in an integrated manner, thereby expanding mutual benefits with customers. To achieve this, we will always listen carefully to our customers and be responsive, growing together over the long term and co-creating a better future.

Message



Fumihiko Kaminaga

Senior Vice President & General Manager
Division Officer,
Global Sales Division

Our business covers a wide range of technology areas, from cutting-edge processes to power semiconductors. By leveraging our large-scale customer base spanning hundreds of companies, we provide timely and optimal proposals for diverse applications, including data centers, automotive, and energy as well as AR/VR and silicon photonics. By formulating medium- to long-term roadmaps with customers and providing optimal solutions, we contribute to sustainable value creation.



Sales

Key Themes for
Medium- to Long-
term Value
Creation

Increasing mutual profits by
providing the Best Products,
Best Technical Service

Improving our responsiveness
to customers and customer
satisfaction

Management Resources to Be Invested

Intellectual capital

A global sales and service system

in which the Account Sales Division, the Global Sales Division, business units and overseas subsidiaries coordinate with one another



Intellectual capital

Broad-ranging knowledge and comprehensive technological capabilities

born from our diverse product lineup



Social and relationship capital

Mutual trust with customers

built through many years of performance records



Differentiation Points

**Co-creation with
Customers**

Global Operations

Optimal Solutions

**Unique Customer
Satisfaction Survey**

Value Created

High-value-added products

incorporating innovative technologies through concurrent evaluation of technologies anticipating four generations and beyond in the future

Product lineup that responds to diverse applications and
optimal solutions that integrate multiple processes

Sole strategic partner

through close collaboration throughout the entire Group

Related Main Risks

Risk Management P. 65-66

Risk 1

Market Fluctuations

Risk 3

Geopolitics

Risk 10

Information Security

Risk 16

Business Locations

Sales

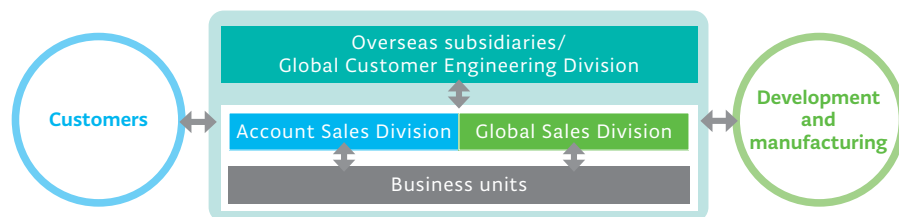
Key
Theme

Increasing mutual profits by providing the Best Products, Best Technical Service

Development of Global Operations

We established the Account Sales Division and the Global Sales Division and strive to swiftly offer the technology, services and solutions our customers need to become the sole strategic partner for our customers. In the Account Sales Division, we receive and leverage next-generation technology needs shared by major semiconductor manufacturers such as those in memory, logic, and foundry businesses driving current momentum in the AI device market, to develop cutting-edge technologies. The Global Sales Division responds to the needs of domestic and overseas customers that handle products for the rapidly-growing Chinese market and the industrial IoT market.

These divisions work in close coordination with business units, development and manufacturing divisions, service divisions, and overseas subsidiaries to conduct comprehensive sales activities. By engaging in communication with our customers—from their management to on-site engineers—we continue to further strengthen our responsiveness and expand global operations as ONE TEL.



Proposing Customer Solutions Leveraging a Wide Range of Product Lineup

We are expanding the wide range of our product lineup, including equipment for the four key processes of deposition, coater/developer, etch and cleaning in the frontend process, as well as equipment for testing and bonding/debonding processes in the backend process. By leveraging this product lineup in our proposal activities, we will solve customers' issues and contribute to the manufacturing of highly competitive semiconductors.

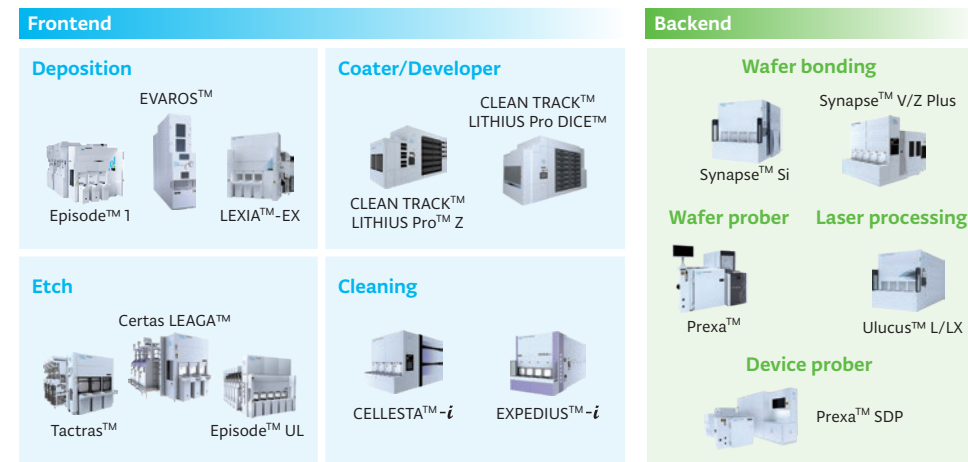
In the frontend process, we are undertaking the development of equipment with innovative and extreme processing performance, centered on (1) deposition systems that accommodate

new materials and structure while utilizing batch, semi-batch and single-wafer capabilities, enabling precise control of film thickness and film quality, (2) coater/developers for EUV lithography including leading-edge High NA, (3) etch systems that enable precision patterning of fine features and the fabrication of deep holes and trenches with high selectivity, and (4) cleaning systems that remove particles and residues—which are causes of yield loss—without causing the collapse of fine patterns.

In the backend process, we also possess wafer probers used in wafer testing and bonding/debonding systems that realize 3D packaging. In the future, there will be a demand for further improvements in the performance of semiconductors as well as scaling technology using cutting-edge nodes to improve the performance in generative AI services and expand the application range. To achieve this higher performance, the adoption of advanced packaging technology (Chiplet) that combines singulated dies is accelerating. We provide KGD* test equipment, which is essential for Chiplet, and we are actively providing solutions for bonding processes of diced devices as well.

Looking ahead, as device scaling continues to advance, including through the adoption of Chiplet technology, we will provide solutions to customers' challenges by leveraging our broad portfolio of frontend and backend products, together with our process integration capabilities that span across manufacturing processes.

* KGD: Known Good Die/Device. A bare die or device that has been tested and proven defect-free.



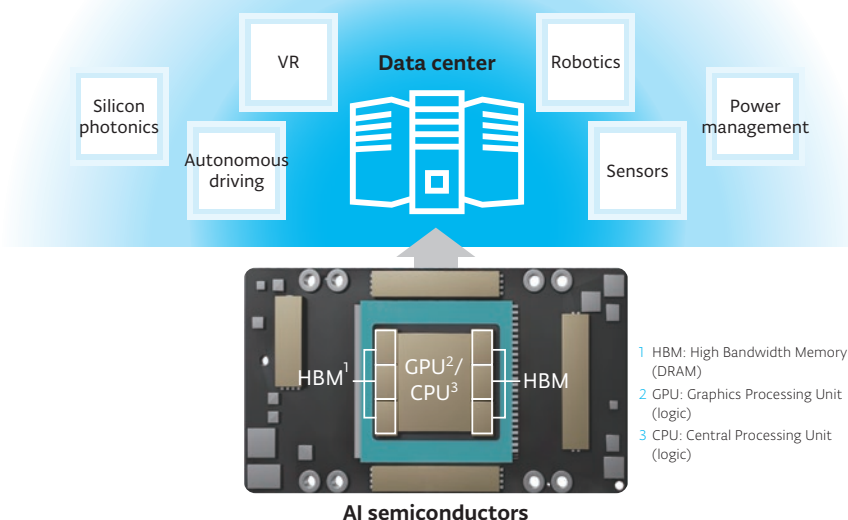
Sales

Key
Theme

Improving our responsiveness to customers and customer satisfaction

Expansion into the Diversified Semiconductor Market

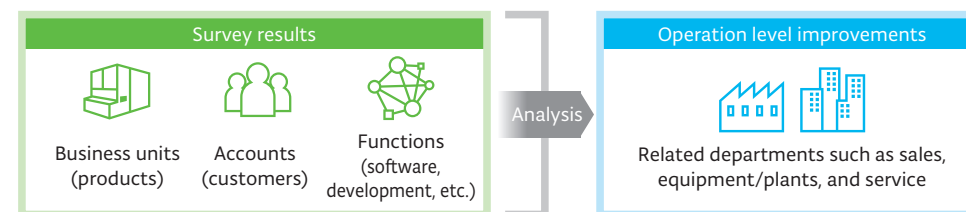
In recent years, the semiconductor market has been rapidly expanding and evolving, driven by advanced logic, memory, and advanced packaging for AI data centers, along with related technologies, such as silicon photonics and power management, as well as autonomous driving, VR, various sensors, and future robotics applications. Specialization by application as well as collaboration are advancing, and value is increasing along with changes in the entire ecosystem. Under these circumstances, we provide equipment with proprietary technologies for enabling advanced functions while also providing an optimal product lineup for new applications and a wider range of functions, drawing on our large installed base, extensive experience, and use of the latest technologies. We also propose a variety of solutions including improving the productivity and extending the service life of equipment in our installed base.



Initiatives for Improvement of Customer Satisfaction

Since our founding, we have been working to build solid relationships of mutual trust with customers by enhancing customer satisfaction, which we value highly. We co-create future technology roadmaps with the semiconductor manufacturers that are our customers to promote the concurrent evaluation of technologies for the next four generations and beyond and accelerate Shift Left development, while also striving to optimize cost. This enables us to provide optimal solutions that contribute to customer value creation and to offer highly competitive products that help improve customers' productivity by improving the yield rate of devices and maximizing equipment utilization rate. Furthermore, at customer sites around the world, we are continuously implementing customer-oriented initiatives such as assigning our company engineers to ramp the equipment up to its maximum performance quickly, proposing effective solutions to identified technical issues and providing feedback on next-generation equipment.

In addition to these activities, we conduct our own Customer Satisfaction Survey* every year. In the fiscal 2026 survey, we received responses from approximately 1,800 respondents (response rate: 84.2%). We analyzed the results and used them in our PDCA cycle to make improvements at the operation level.



Our activities were highly evaluated and we received best awards consecutively from many of our customers in fiscal 2026. We will continue to provide the Best Products with innovative technology and Best Technical Service with high added value and strive to further improve customer satisfaction.

* "Customer Satisfaction" on our website www.tel.com/sustainability/customer/satisfaction/index.html

Installation and Maintenance Services

Message

In a market that is expected to continue to expand, we provide safe and high-quality Best Technical Service with high added value for new equipment with leading-edge technology and the industry-leading installed base. We are also continuously conducting safety activities around the world. To effectively utilize our human resources, we assign personnel based on actual business conditions and use Epsira™ DX solutions to improve operational efficiency. Furthermore, we also use Epsira™ for data analysis and knowledge management, earning the absolute trust of our customers by accurately understanding their needs and swiftly providing solutions. Through measures such as these, we strive to satisfy our customers and further enhance corporate value by providing the Best Technical Service, which contributes to the stable operation and improved productivity not only of leading-edge equipment, but also of various generations of equipment that support diverse applications.



Soichiro Kori

Vice President & General Manager
Division Officer, Global Customer
Engineering Division



Installation and Maintenance Services

Key Themes for
Medium- to Long-
term Value
Creation

Reinforcing human resources
development and the
succession and evolution
of the Tokyo Electron identity

Enhance customer
satisfaction by providing
Best Technical Service with
high added value

Management Resources to Be Invested

Intellectual capital

Service support infrastructure

at **102** sites located
in **18** countries and
regions of the world



Intellectual capital

Service database and
remote support system

that utilizes digital technologies,
knowledge management etc.



Human capital

Global Customer Engineering Division
Operation with a total of

approximately
6,300 people



Differentiation Points

Field Engineer

Installed Base

Efficiency through DX

Equipment Lifecycle

Value Created

Comprehensive services

resulting from global expansion that include
everything from equipment installation to
maintenance

Contribution toward the long-term
steady operation of equipment

across a variety of generations

Services with high technical
capabilities

contributing to improving customers'
productivity

Related Main Risks

➡ Risk Management P. 65-66

Risk **5**

Safety

Risk **6**

Quality

Risk **11**

Human
Resources

Risk **16**

Business
Locations

Installation and Maintenance Services

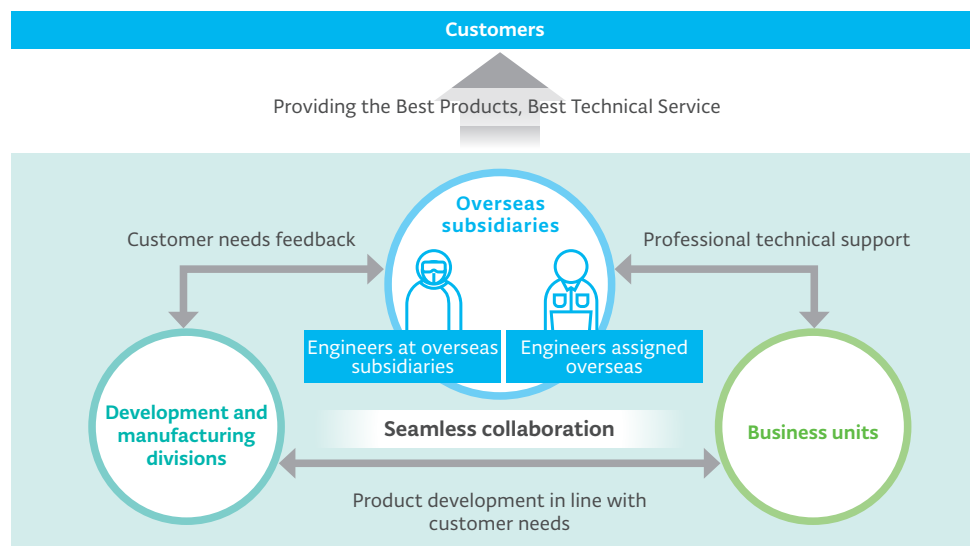
Key
Theme

Reinforcing human resources development and the succession and evolution of the Tokyo Electron identity

Strengthening Field Engineers' Customer Responsiveness

To further expand the scale of our business, it is extremely important to increase the number of field engineers, developing personnel that can promptly play an active role, as well as to effectively improve the skills of existing field engineers. It is also vital that we optimize our resource allocation from a global perspective, concentrating personnel in high demand areas and appropriately transferring personnel with a high level of expertise to the areas that need them.

Due to geopolitical factors and investment support backed by national policies, a growing number of customers are globally expanding their business operations or entering the semiconductor industry for the first time. This is making it even more important to expand and enhance our support sites. We must understand their individual needs and characteristics and go beyond the boundaries of local subsidiaries and business units to appropriately assign human resources with essential capabilities where they are needed, creating a system that helps increase the production capacities of our customers.



We establish a Group-wide common skills management system that meets the standards of Semiconductor Equipment and Materials International (SEMI) and plan to continuously upgrade skills based on the detailed goals established every year. We effectively train newly hired personnel through our "Ichininmae engineer*" development project," a three-year program that begins after hiring and provides new employees with the skills and experience they will need as field engineers. Furthermore, we are expanding our program to reassign engineers who had undergone training at manufacturing sites in Japan to the field after their return to their companies, as part of our education for expert engineers for overseas subsidiaries. In this program, engineers strive not only to deepen their knowledge of equipment technology but also to further improve communication with development and manufacturing divisions. During the program period, engineers from overseas subsidiaries receive support from Japan, enabling them to understand customers' situations in a timely manner and further contribute as site leaders upon returning to their home countries.

As a result of these initiatives, we have earned high praise from our customers for the speed, efficiency, and dedication of our services. We will continue to use feedback from our customers to strengthen our customer responsiveness.

* Ichininmae engineer: Full-fledged engineer

Creation of New Value through Sharing Knowledge and Experience

Employees with abundant work experience publish their insights and what they have learned through their careers on the internal intranet to provide junior and mid-level employees with opportunities to lay out their own career paths and future visions. We have expanded this initiative to our overseas subsidiaries, as well, as we aim to pass on our DNA, such as our customer-oriented approach, openness, and teamwork, to our global junior and mid-level employees, and to create new value while adapting to the changing times.



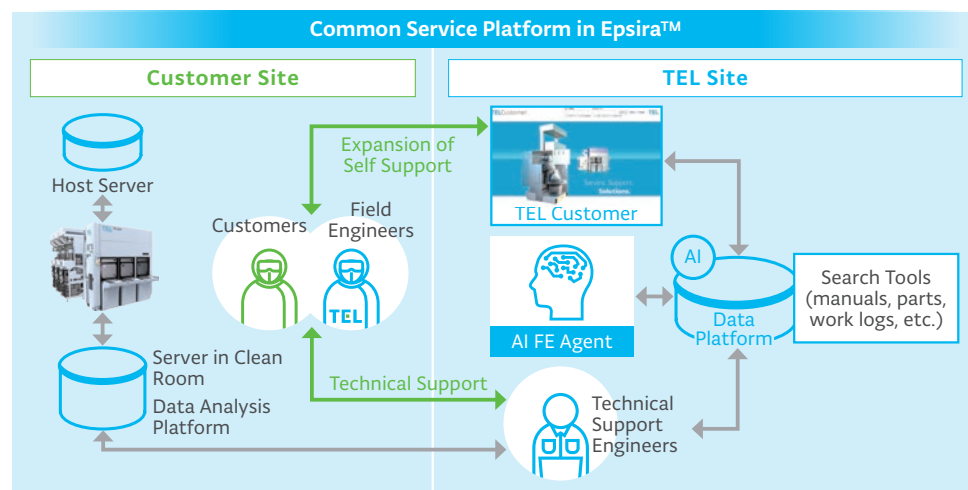
Installation and Maintenance Services

Key
Theme

Enhance customer satisfaction by providing Best Technical Service with high added value

Provision of Best Technical Service with High Added Value

In recent years, there have been increasing calls from customers for us to supply high level support technology for dealing with manufacturing processes that realize scaling and multi-layering of semiconductor devices, to further improve productivity, and to reduce environmental impact. To provide Best Technical Service with high added value that responds to these needs, in addition to developing field engineers, we have rolled out Epsira™ DX solutions, supply services that use digital and information and communication technologies, and strive to raise work efficiency.



Work log data for day-to-day service support and various information related to devices are centrally managed on a global scale. To effectively utilize this centrally managed data, we are continuing to develop our data platform and using that platform to introduce various DX tools and enable access from clean rooms.

Field engineers can use various tools to access past examples of troubleshooting, manuals, work logs, improvement logs, and the like via the data platform. The goal is to accelerate

and improve the accuracy of their troubleshooting to provide even faster and higher quality services. We have also rolled out remote support tools for engineers in customer clean rooms. By efficiently analyzing equipment data, we dynamically provide effective support. Through our deployment of Epsira™, we are improving our customers' productivity.

We provide a wide range of contracted services for the stable operation of equipment, such as services in which our field engineers are stationed at customers' manufacturing sites to maintain their equipment, as well as a comprehensive contracted service (TEL SERVICE ADVANTAGE™) in which we offer pay-as-you-go or flat-rate maintenance services and we supply maintenance/consumable parts and repairs in an integrated manner. Furthermore, we aggregate and analyze data output from equipment, predict when major parts are likely to fail and suggest replacement in advance so that we can prevent problems, stabilize process capabilities, and help improve our customers' equipment utilization rates.

Further Initiatives for the Improvement of On-site Safety¹

The number of workplace incidents per 200,000 work hours (TCIR²) was 0.22, realizing an industry-leading safety environment in the semiconductor production equipment industry. We closely analyze close calls (dangerous cases that had the potential of becoming incidents) reported by our field engineers, along with accidents caused by human error, and strive to improve on-site safety activities by sharing information that can help prevent accidents with the safety promotion department of our subsidiaries. At newly constructed semiconductor plants around the world, we strive to establish safe working environments by dispatching safety officers from Japan and having them work together with local personnel to perform checklist-based assessments both inside and outside clean rooms. Furthermore, to foster a focus on safety throughout the organization, we regularly provide training to all engineers using digital technologies such as VR and on-demand video streaming systems.

¹ Safety P.61

² TCIR: Total Case Incident Rate